

Fig. 1

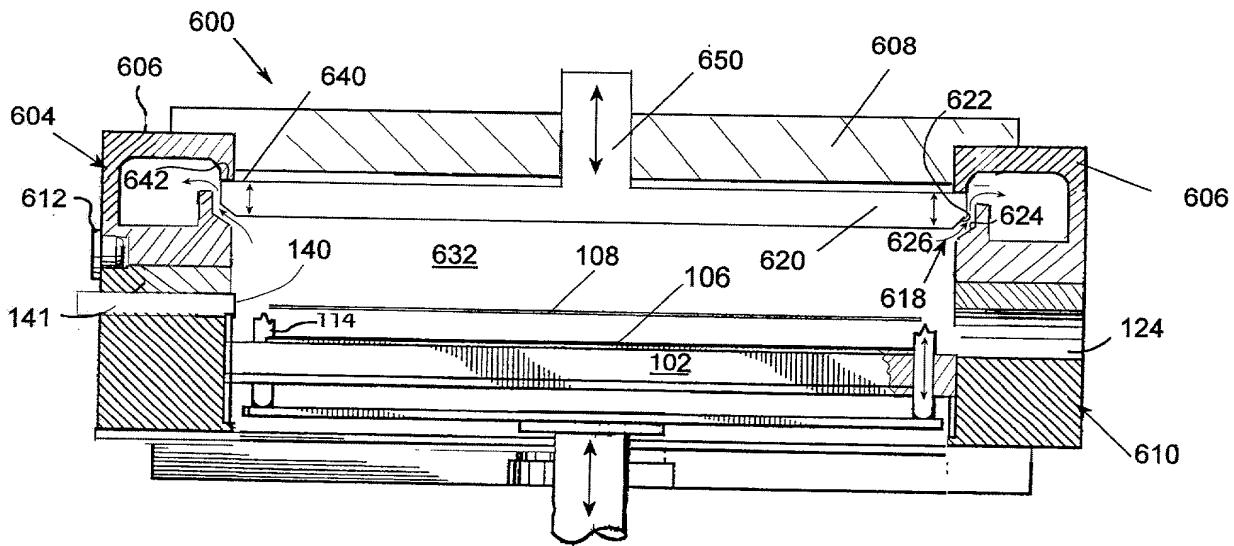
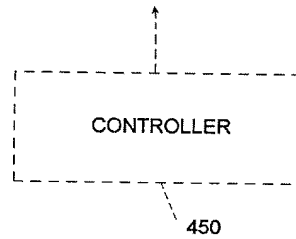


Fig. 5

FIG. 2 is a flowchart of a process for depositing a material on a substrate. The process begins with inserting the substrate into a chamber (122). The non-sealing flow restrictor is closed (170), and the first deposition gas is admitted to pressurize the chamber (173). The substrate is soaked in the deposition gas (174). The non-sealing flow restrictor is opened (180), and the purge gas and residual deposition gas are pumped out of the chamber (204). The process then enters a loop where the non-sealing flow restrictor is closed (208), the second deposition gas is admitted to pressurize the chamber (210), the substrate is soaked in the deposition gas (212), the non-sealing valve is opened (216), and the purge gas and residual deposition gas are pumped out of the chamber (218). This loop is repeated until the substrate is removed from the chamber (220).

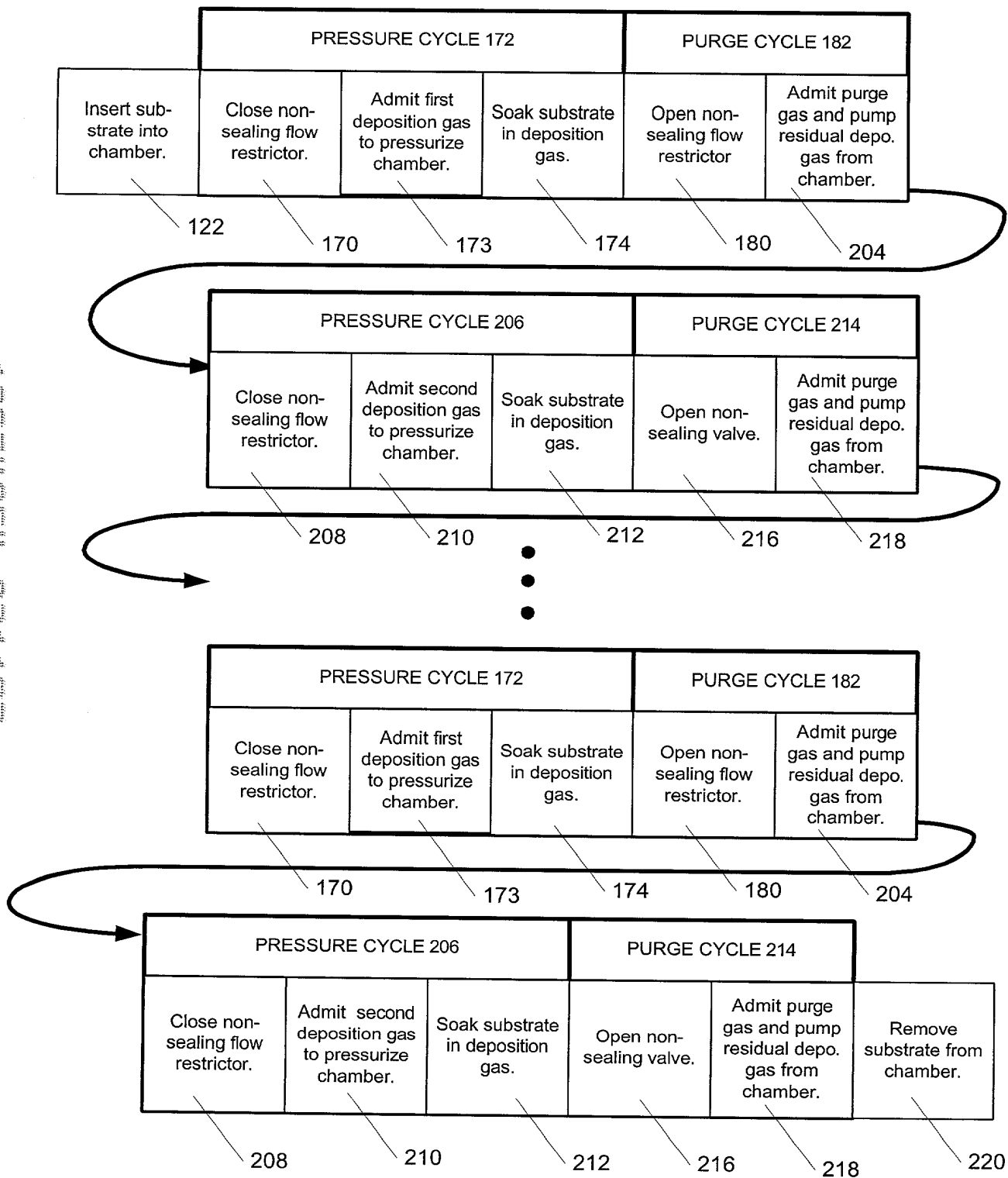


Fig. 2

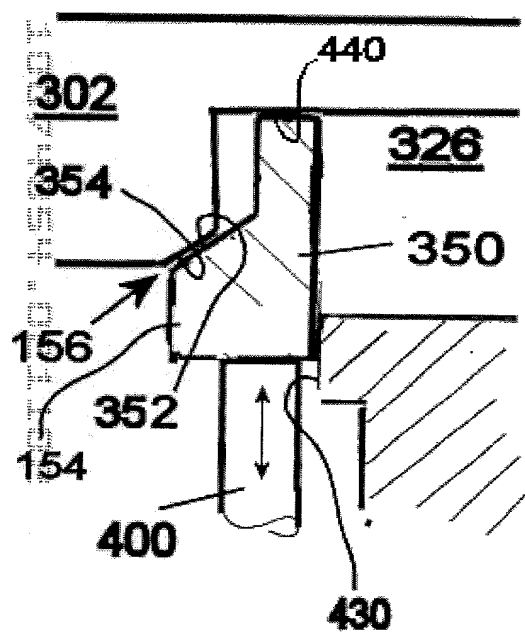


Fig. 3

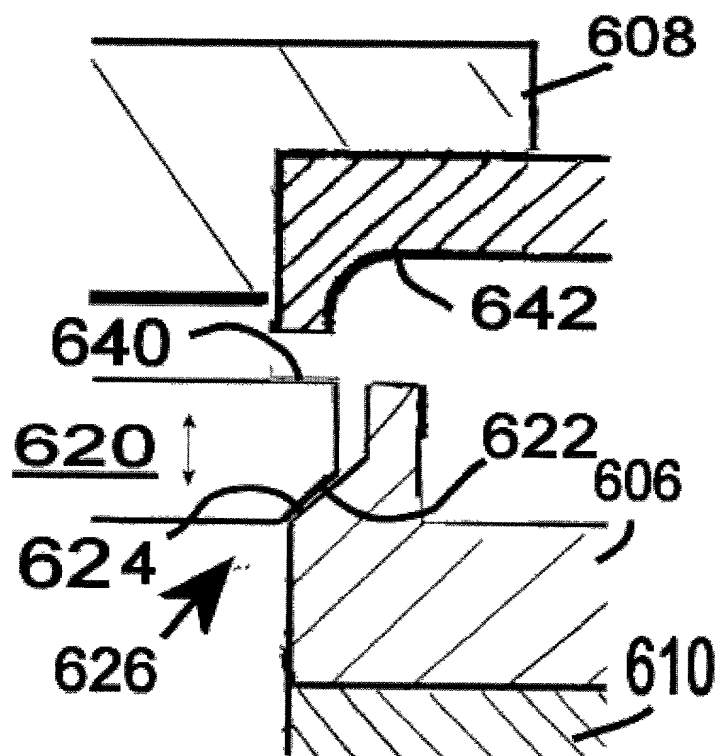


Fig. 6

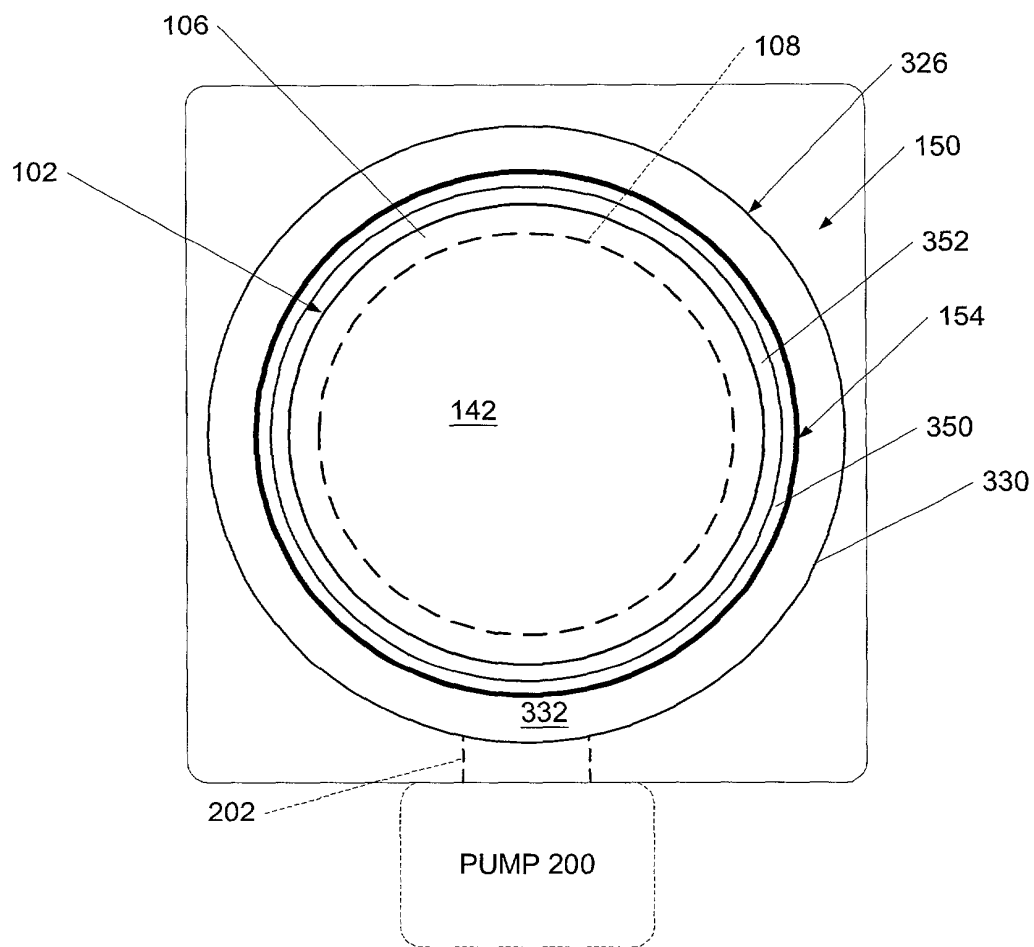


Fig. 4